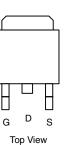
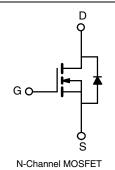


Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	60					
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.0035					
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.0039					
I _D (A)	120					
Configuration	Single					

TO-263





FEATURES

- TrenchFET[®] Power MOSFET
- Package with Low Thermal Resistance
- AEC-Q101 Qualified^d
- 100 % $\rm R_g$ and UIS Tested
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>



ORDERING INFORMATION				
Package	TO-263			
Lead (Pb)-free and Halogen-free	SQM120N06-3m5L-GE3			

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	60	M		
Gate-Source Voltage		V _{GS}	± 20	V		
Continuous Drain Current ^a	T _C = 25 °C	1	120			
	T _C = 125 °C	l I _D	120			
Continuous Source Current (Diode Conduction) ^a	I _S	120	А			
Pulsed Drain Current ^b	I _{DM}	480				
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	100			
Single Pulse Avalanche Energy		E _{AS}	500	mJ		
Mauinum Daura Diasin atianh	T _C = 25 °C	D	375	W		
Maximum Power Dissipation ^b	T _C = 125 °C	P _D	125	vv		
Operating Junction and Storage Temperature Ran	ige	T _J , T _{stg}	-55 to +175	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)		R _{thJC}	0.4	0/10		

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

1

SQM120N06-3m5L



Vishay Siliconix

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static					•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \ \mu A$		60	-	-	v	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$		2.0	2.5	v	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	900	1	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	120	-	-	Α	
		$V_{GS} = 10 V$	I _D = 30 A	-	0.0028	0.0035		
Drain-Source On-State Resistance ^a	Р	$V_{GS} = 10 V$	$I_D = 30 \text{ A}, \text{T}_\text{J} = 125 \ ^\circ\text{C}$	-	-	0.0064	Ω	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	-	0.0080		
		$V_{GS} = 4.5 V$	I _D = 20 A	-	0.0031	0.0039	1	
Forward Transconductanceb	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		-	190	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	11 755	14 700		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	_S = 0 V V _{DS} = 25 V, f = 1 MHz		1112	1400	pF	
Reverse Transfer Capacitance	C _{rss}			-	481	605	1	
Total Gate Charge ^c	Qg			-	220	330	nC	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 110 \text{ A}$	-	35	-		
Gate-Drain Charge ^c	Q _{gd}		1 [35	-	1	
Gate Resistance	R _g	f = 1 MHz		0.6	1.3	2	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	19	29		
Rise Time ^c	t _r	$\label{eq:VDD} \begin{array}{l} V_{DD}=30~\text{V},~\text{R}_{\text{L}}=0.27~\Omega\\ \text{I}_{\text{D}}\cong110~\text{A},~\text{V}_{\text{GEN}}=10~\text{V},~\text{R}_{\text{g}}=2.5~\Omega \end{array}$		-	23	35	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	83	125		
Fall Time ^c	t _f			-	35	53		
Source-Drain Diode Ratings and Char	acteristics ^b				•			
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	I _F :	= 50 A, V _{GS} = 0	-	0.8	1.5	V	

Notes

a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

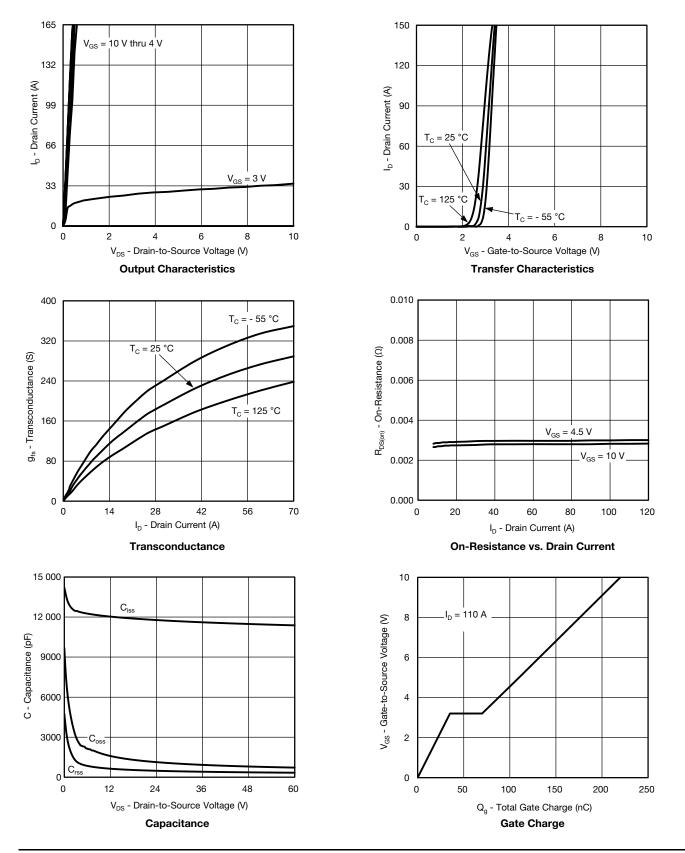
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



S13-2117-Rev. A, 07-Oct-13

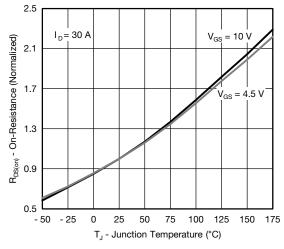
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Document Number: 63814

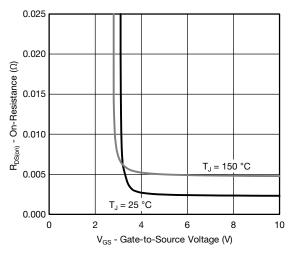
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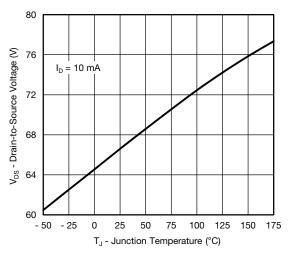
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)







On-Resistance vs. Gate-to-Source Voltage

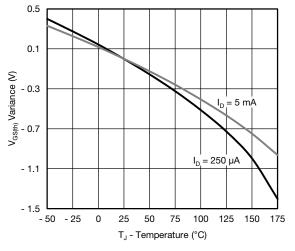


Drain Source Breakdown vs. Junction Temperature

T_J = 150 10 I_s - Source Current (A) 1 T_J = 25 °C 0.1 0.01 0.001 0.0 0.2 0.4 0.6 0.8 1.0 1.2 V_{SD} - Source-to-Drain Voltage (V)

100

Source Drain Diode Forward Voltage



Threshold Voltage

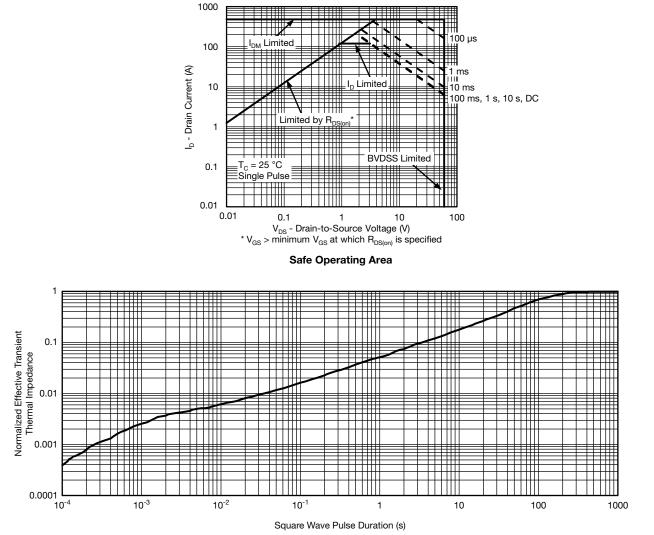
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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)

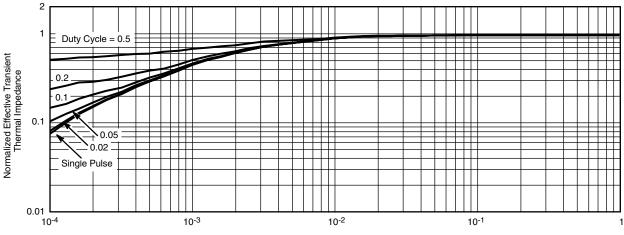


Normalized Thermal Transient Impedance, Junction-to-Ambient

5



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

Note

· The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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6



TO-263 (D²PAK): 3-LEAD









DETAIL A (ROTATED 90°)



		INCHES		MILLIMETERS		
DIM.		MIN.	MAX.	MIN.	MAX.	
А		0.160	0.190	4.064	4.826	
	b	0.020	0.039	0.508	0.990	
	b1	0.020	0.035	0.508	0.889	
	b2	0.045	0.055	1.143	1.397	
с*	Thin lead	0.013	0.018	0.330	0.457	
C	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
CI	Thick lead	0.023	0.027	0.584	0.685	
	c2	0.045	0.055	1.143	1.397	
	D	0.340	0.380	8.636	9.652	
	D1	0.220	0.240	5.588	6.096	
	D2	0.038	0.042	0.965	1.067	
	D3	0.045	0.055	1.143	1.397	
D4		0.044	0.052	1.118	1.321	
	E	0.380	0.410	9.652	10.414	
	E1	0.245	-	6.223	-	
	E2	0.355	0.375	9.017	9.525	
E3		0.072	0.078	1.829	1.981	
	е	0.100 BSC		2.54 BSC		
	К	0.045	0.055	1.143	1.397	
L		0.575	0.625	14.605	15.875	
L1		0.090	0.110	2.286	2.794	
L2		0.040	0.055	1.016	1.397	
L3		0.050	0.070	1.270	1.778	
L4		0.010 BSC		0.254 BSC		
М		-	0.002	-	0.050	
ECN: T13-0707-Rev. K, 30-Sep-13 DWG: 5843						

Notes

- 1. Plane B includes maximum features of heat sink tab and plastic. 2. No more than 25 % of L1 can fall above seating plane by
- max. 8 mils.3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB.
 - Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

This feature is for thick lead.

Revison: 30-Sep-13



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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